LOGITECH WSB2 WAFER SUBSTRATE BONDING UNIT

Bonding Specifications:

- **Bond Equipment :** Logitech WSB2 Wafer to Substrate Bonder.
- **Bond Temp :** 85 C.
- **Wax Soak Time :** 5 mins.
- **Bond Time :** 15 mins.
- **Bond Wax :** Quartz .
- **Vacuum Level :** 1.5 to 3.5 E-1mbar.
- **Applied Pressure :** 15 psi